

REMARKS

Claim 6 is are pending in this application. By this Amendment, claim 6 has been amended and claims 7 - 11 have been canceled without prejudice or disclaimer. Applicants respectfully submit that no new matter has been added. It is believed that this Amendment is fully responsive to the Office Action dated May 7, 2002.

As To The Merits:

As to the merits of this case, the Examiner sets forth the following rejection:

claims 6-11 stand rejected under 35 U.S.C. § § § § 102(e) as being anticipated by Chigawa et al. (of record).

This rejection is respectfully traversed.

Regarding Chigawa, the Examiner specifically relies on Figure 31A for teaching the features of independent claim 6. However, the bump 4 of Fig. 31A does not contact a concave surface of pad 6 as required by claim 6. In other words, Chigawa fails to disclose *a board having pads so that each of the bumps is joined to a corresponding one of the pads, each of the pads per se having a concave surface with which a corresponding one of the bumps contact*, as called for in independent claim 6.

AMENDMENT

09/805,559

Moreover, Fig. 31A does not illustrate a final product. Instead, Fig. 31A illustrates a manufacturing step for the manufacture of the semiconductor device shown in Fig. 27. However, in Fig. 27, the bump 4 also does not contact a concave surface of pad 6, as required by claim 6.

In view of the aforementioned amendments and accompanying remarks, claim 6, as amended, is in condition for allowance, which action, at an early date, is requested.

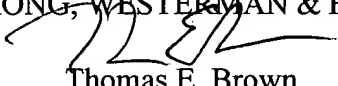
If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

Attached hereto is a marked-up version of the changes made to the by the current amendment. The attached page is captioned "Version with markings to show changes made."

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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PATENT TRADEMARK OFFICE

Enclosures: Version with markings to show changes made  
Q:\FLOATERS\TEB\feb\98\980404\A\Second Amendment

IN THE CLAIMS:

Claim 6 has been AMENDED to read as follows:

6. (Twice Amended) A structure comprising:
- a semiconductor device having bumps;
  - a board having pads so that each of the bumps is joined to a corresponding one of the pads, each of the pads <sup>in itself, intrinsically</sup> per se having a [deformed portion] concave surface with which a corresponding one of the bumps contacts; and
  - an insulating adhesive provided between the semiconductor device and the board,
- wherein
- an end of each of the bumps has a diameter smaller than other portions of the bumps so as to facilitate deformation of the pad when bumps are pressed against the pads and to form a space in which the insulating adhesive is filled, and
- wherein
- contraction of the insulating adhesive maintains joints of the bumps and the pads, said joints being made by deformation of the pads.

Claims 7 - 11 have been CANCELED without prejudice or disclaimer.